

What is claimed is:

1. An electronic component wherein a lead frame is attached to an element with an electrically conductive adhesive,
5 the electronic component being characterized in that the lead frame has an adhesive filling portion formed at a part thereof having a lower surface opposed to the element, the filling portion having inside thereof filled with the conductive adhesive.
- 10 2. An electronic component according to claim 1 wherein the adhesive filling portion is one of a hole, cavity, cutout and groove formed in the lead frame.
- 15 3. An electronic component according to claim 2 wherein the lead frame is provided with a plurality of grooves intersecting one another and divided into a plurality of frame segments by the grooves.
4. An electronic component according to claim 1 which is a solid electrolytic capacitor and wherein the element is a capacitor element.